

Abstract

Method of, and device for, fitting components on substrates

In order to achieve a defined contact pressure of components (2) on substrates, at least those parts of the retaining device (3) which are directed toward the component (2) are coupled in relation to the component-fitting head (4) by a spring (6). As the components (2) are received from feed arrangements (8), said spring causes said components (2) to be accelerated to an excessively pronounced extent, which may result in the components (2) falling off.

By virtue of the device and the method according to the invention, the spring coupling is replaced by a fixed coupling at the moment at which the component (2) is received from the feed arrangement (8). The acceleration acting on the component (2) decreases, with the result that, with the same acceleration acting on the component (2), the capacity for fitting components is improved by higher receiving-movement speeds.

Figure 4